

1.25 A sensitive gate SCR

Features

- on-state rms current: 1.25 A
- repetitive peak off-state voltage: 600 V and 800 V
- gate triggering current: 50 and 200 µA

Applications

- ground fault circuit interrupters
- overvoltage crowbar protection in power supplies
- capacitive ignition circuits

Description

The X02 SCR can be used as the on/off function in applications where topology does not offer high current for gate triggering.

This device is optimized in forward voltage drop and inrush current capabilities for reduced power losses and high reliability in harsh environments.

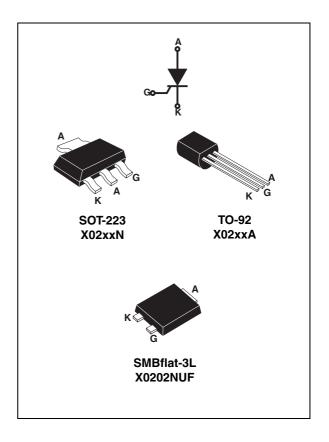


Table 1. Device summary

Order code	Voltage		Sanaitivity u.A	Poekage	
Order code	600 V	800 V	— Sensitivity μA	Package	
X0202MA	Y		200	TO-92	
X0202MN	Y	200		SOT-223	
X0202NA		Υ	200	TO-92	
X0202NN		Y	200	SOT-223	
X0205MA	Y		50	TO-92	
X0205NA		Υ	50	TO-92	
X0202NUF		Y	200	SMBflat-3L	

Characteristics X02

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Table 2. Absolute ratings (limiting values, $T_J = 25$ °C unless otherwise specified)

Symbol	Parameter	Value	Unit		
		TO-92	T _L = 63 °C		
I _{T(RMS)}	On-state rms current (180 °Conduction angle)	SOT-223	T _{tab} = 99 °C	1.25	Α
		SMBflat-3L	T _{tab} = 111 °C		
		TO-92	T _L = 63 °C		
IT _(AV)	Average on-state current (180 °Conduction angle)	SOT-223	T _{tab} = 99 °C	0.8	Α
		SMBflat-3L	T _{tab} = 111 °C		
	Non repetitive curren peak on state current	$t_p = 8.3 \text{ ms}$	T - 25 °C	25	Α
I _{TSM}	Non repetitive surge peak on-state current	t _p = 10 ms	T _j = 25 °C	22.5	^
l ² t	I^2 t Value for fusing $t_p = 10 \text{ ms}$		T _j = 25 °C	2.5	A ² s
di/dt	Critical rate of rise of on-state current $I_G = 2 \times I_{GT}$, $t_r \le 100 \text{ ns}$	F = 60 Hz	T _j = 125 °C	50	A/µs
I _{GM}	Peak gate current $t_p = 20 \ \mu s \qquad T_j = 125 \ ^{\circ} C$		1.2	Α	
P _{G(AV)}	Average gate power dissipation	0.2	W		
T _{stg} T _j	Storage junction temperature range Operating junction temperature range	- 40 to + 150 - 40 to + 125	°C		

Table 3. Electrical characteristics ($T_J = 25$ °C unless otherwise specified)

Symbol	Test conditions		X0202	X0205	Unit		
		Min.		20			
I _{GT}	V_D = 12 V, R_L = 140 Ω	= 12 V, R_L = 140 Ω	Max.	200	50	μΑ	
V _{GT}				0.8		V	
V _{GD}	$V_D = V_{DRM,} R_L = 3.3 \text{ k}\Omega$, $R_{GK} = 1 \text{ k}\Omega$	Min.	0.1		V		
V _{RG}	I _{RG} = 10 μA	Min.	8	3	V		
I _H	I_T = 50 mA, R_{GK} = 1 k Ω	Max.	5	5	mA		
ΙL	I_G = 1 mA, R_{GK} = 1 k Ω			(6	mA	
dV/dt	$V_D = 67\% V_{DRM_j} R_{GK} = 1 \text{ k}\Omega$ $T_j = 110 \text{ °C}$		Min.	10	15	V/µs	

Table 4. Static electrical characteristics

Symbol	Test conditi	X0202	X0205	Unit		
V _{TM}	$I_{TM} = 2.5 \text{ A}, t_p = 380 \mu\text{s}$	T _j = 25 °C		1.45		V
V _{TO}	Threshold voltage	T _j = 125 °C		0.9		V
R _d	Dynamic resistance			20	00	mΩ
I _{DRM} I _{RRM}	V -V B -1k0	T _j = 25 °C	_j = 25 °C		5	μΑ
	$V_{DRM} = V_{RRM}, R_{GK} = 1 \text{ k}\Omega$	T _j = 125 °C		50	00	μΑ

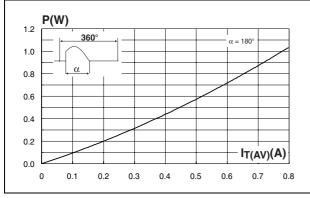
X02 Characteristics

Table 5. Thermal resistances

Symbol	Paran		Value	Unit		
R _{th(j-l)}	Junction to leads (DC)	TO-92		60		
R _{th(j-t)}	Junction to tab (DC)	SOT-223	•	25		
R _{th(j-t)}	Junction to tab (DC)	SMBflat-3L	Max.	14	°C/W	
			TO-92	iviax.	150	C/VV
R _{th(j-a)}	Junction to ambient (DC)	$S = 5 \text{ cm}^2$	SOT-223	•	60	
		SMBflat-3L	·	75		

Figure 1. Maximum average power dissipation versus average on-state current (full cycle)

Figure 2. Average and DC on-state current versus tab (SOT-223, SMBflat-3L) or lead (TO-92) temperature



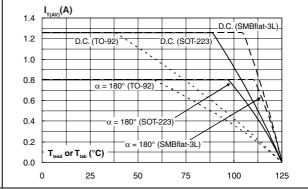
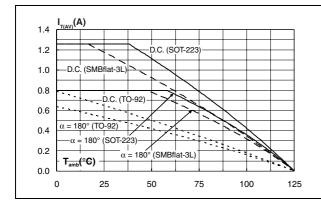
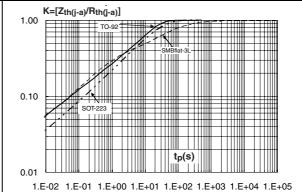


Figure 3. Average and DC on-state current versus ambient temperature

Figure 4. Relative variation of thermal impedance junction to ambient versus pulse duration

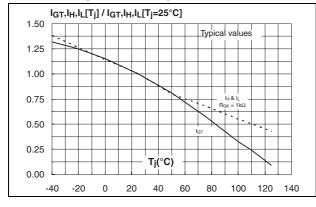




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Figure 5. Relative variation of triggering, holding and latching current versus junction temperature

Figure 6. Relative variation of holding current versus gate-cathode resistance (typical values)



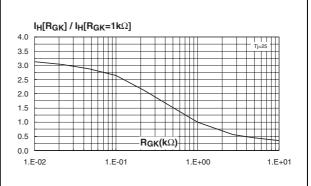
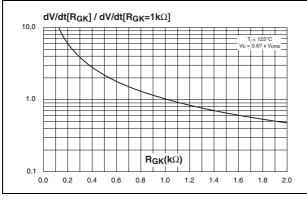


Figure 7. Relative variation of dV/dt immunity Figure 8. versus gate-cathode resistance (typical values)

Relative variation of dV/dt immunity versus gate-cathode capacitance (typical values)



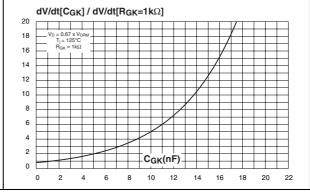
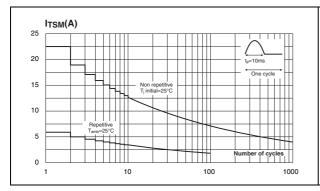


Figure 9. Surge peak on-state current versus number of cycles

Figure 10. Non repetitive surge peak on state current for a sinusoidal pulse and corresponding value of I²T



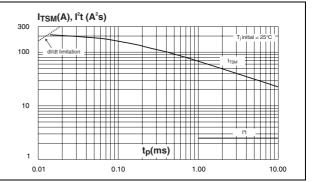
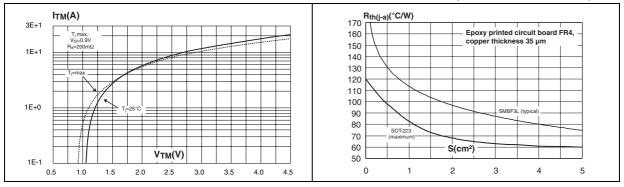
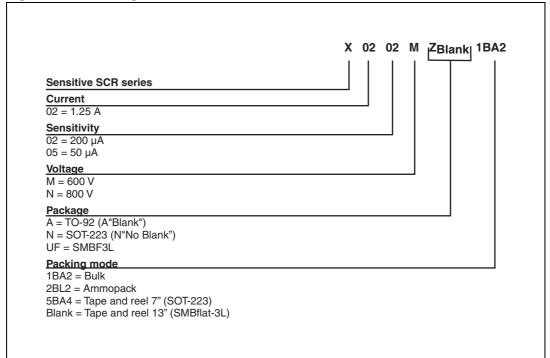


Figure 11. On-state characteristics (maximum Figure 12. Thermal resistance junction to ambient versus copper surface under tab (SOT-223, SMBflat-3L)



2 Ordering information scheme

Figure 13. Ordering information scheme



Package information X02

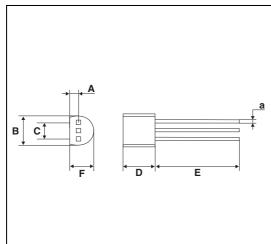
3 Package information

- Epoxy meets UL94, V0
- Lead-free packages

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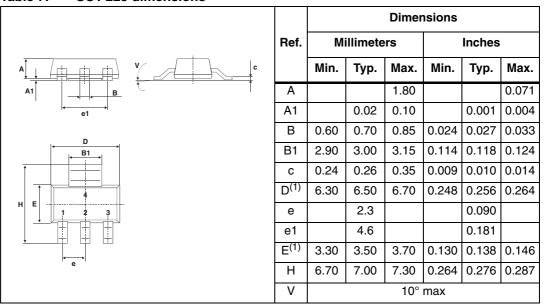
Table 6. TO-92 dimensions



		Dimensions							
Ref	Mi	llimete	rs		Inches				
	Min.	Тур.	Max.	Min.	Тур.	Max.			
Α		1.35			0.053				
В			4.70			0.185			
С		2.54			0.100				
D	4.40			0.173					
Е	12.70			0.500					
F			3.70			0.146			
а			0.50			0.019			

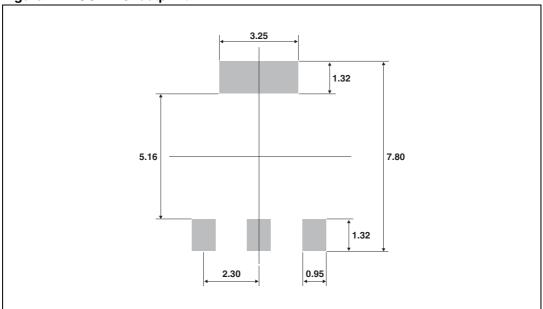
X02 Package information

Table 7. SOT-223 dimensions



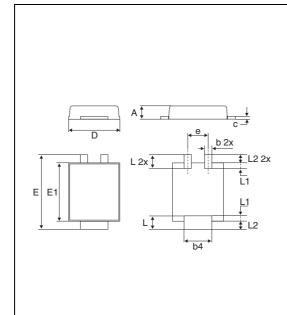
^{1.} Do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.15mm (0.006inches)

Figure 14. SOT-223 footprint



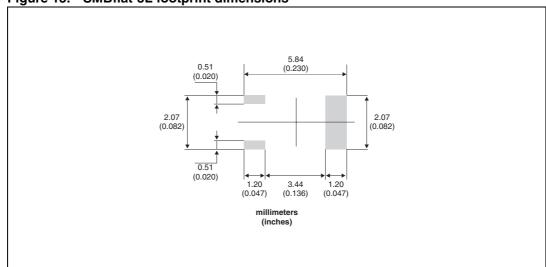
Package information X02

Table 8. SMBflat-3L dimensions



		Dimensions						
Ref.	Millime		eters		Inches			
	Min.	Тур.	Max.	Min.	Тур.	Max.		
Α	0.90		1.10	0.035		0.043		
b	0.35		0.65	0.014		0.026		
b4	1.95		2.20	0.07		0.087		
С	0.15		0.40	0.006		0.016		
D	3.30		3.95	0.130		0.156		
Е	5.10		5.60	0.201		0.220		
E1	4.05		4.60	0.156		0.181		
L	0.75		1.50	0.030		0.059		
L1		0.40			0.016			
L2		0.60			0.024			
е		1.60			0.063			

Figure 15. SMBflat-3L footprint dimensions



X02 Package information

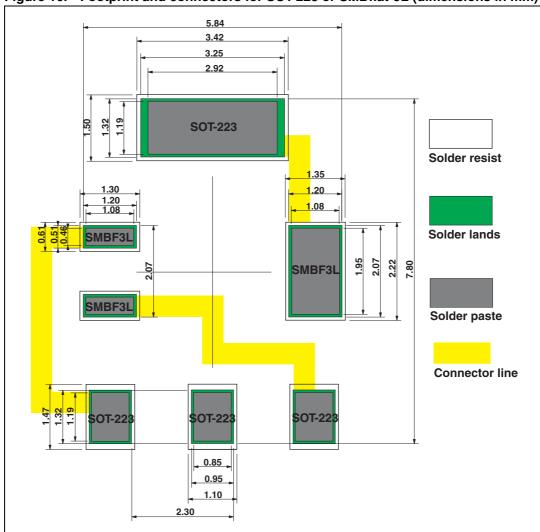


Figure 16. Footprint and connectors for SOT-223 or SMBflat-3L (dimensions in mm)

Ordering information X02

4 Ordering information

Table 9. Ordering information

Order code	Marking	Package	Weight	Base qty	Delivery mode
X0202MA 1BA2	X0202 MA	TO-92	0.2 g	2500	Bulk
X0202MA 2BL2	X0202 MA	TO-92	0.2 g	2000	Ammopack
X0202MN5BA4	X2M	SOT-223	0.12 g	1000	Tape and reel
X0202NA 1BA2	X0202 NA	TO-92	0.2 g	2500	Bulk
X0202NA 2BL2	X0202 NA	TO-92	0.2 g	2000	Ammopack
X0202NN5BA4	X2N	SOT-223	0.12 g	1000	Tape and reel
X0205MA 1BA2	X0205 MA	TO-92	0.2 g	2500	Bulk
X0205MA 2BL2	X0205 MA	TO-92	0.2 g	2000	Ammopack
X0205NA 1BA2	X0205 NA	TO-92	0.2 g	2500	Bulk
X0202NUF	X2N	SMBflat-3L	46.914 mg	5000	Tape and reel

5 Revision history

Table 10. Document revision history

Date	Revision	Changes			
Sep-2000	3	Previous issue			
14-Jan-2011	4	Added SMBflat-3L package and ECOPACK statement.			

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